

Title (en)  
SEMICONDUCTOR CHIP PACKAGING AND METHOD FOR THE PRODUCTION THEREOF

Title (de)  
HALBLEITERCHIPPACKUNGEN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)  
BOITIERS DE PUCES DE SEMICONDUCTEUR ET LEUR PROCEDE DE PRODUCTION

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Application  
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Abstract (en)  
[origin: WO9905721A1] The invention relates to a method for producing semiconductor chip packaging using semiconductor chips (1). At least one semiconductor chip (1) is provided with at least one dielectric film (2, 2', 22). At least one opening is made in the at least one film (2, 2', 22). Current paths (40, 42, 30000, 30002) are placed on the at least one film (2, 2', 22) and in the at least one opening in such a way that at least one semiconductor chip connection (1.2) comes into electrical contact with the current paths (40, 42, 3000, 3002) by means of at least one opening.

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